

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5	"425"/\$.ccls. and (injection with (mold or mould)) and (silicon with insert)	US-PGPUB; USPAT	OR	ON	2004/12/10 16:45
L2	5	(injection with (mold or mould)).ti. and (silicon with insert)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/10 17:03
L3	1	(injection with (mold or mould)).ti. and (silicon) and (microstructures or microreplication)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/10 16:48
L4	823	(425/190).CCLS.	US-PGPUB; USPAT	OR	OFF	2004/12/10 16:49
L5	270	4 and (injection with (mold or mould))	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/10 16:49
L6	15	("2621369"   "2651810"   "2976571"   "3781402"   "3810599"   "3951580"   "4422986"   "4479914"   "4666323"   "4712936"   "4797236").PN. OR ("5531582").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/10 17:03
L7	1	(injection with (mold or mould) with (microreplication or microstructures)).ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/10 17:08
L8	25	(injection with (mold or mould) with (micro)).ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/10 17:06
L9	0	("2002098611").PN.	US-PGPUB; USPAT	OR	OFF	2004/12/10 17:06
L10	1	("2002098611").PN.	US-PGPUB; USPAT	OR	OFF	2004/12/10 17:06
L11	149	(injection with (mold or mould)) same (micro-device or microfabricated or microneedle)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/10 17:10
L12	1	("5,512,131").PN.	US-PGPUB; USPAT	OR	OFF	2004/12/10 17:10

L13	141	("2905539"   "4587213"   "4690715"   "5032216"   "5079600"   "5143854"   "5202227"   "5259926").PN. OR ("5512131").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/10 17:10
L14	12	("4614630"   "5250023"   "5304487"   "5498392"   "5879326"   "5885470").PN. OR ("6331266").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/10 17:21
L15	24	("4614630").URPN.	USPAT	OR	ON	2004/12/10 17:29
L16	6	"4307869"	EPO; DERWENT	OR	ON	2004/12/10 17:31
L17	5	"437345"	EPO; DERWENT	OR	ON	2004/12/10 17:31
L18	3	"9748440"	EPO; DERWENT	OR	ON	2004/12/10 17:33
L19	1	"5234571"	EPO; DERWENT	OR	ON	2004/12/10 17:33
L20	1	("5234571").PN.	US-PGPUB; USPAT	OR	OFF	2004/12/10 17:33
L21	15	("5234571").URPN.	USPAT	OR	ON	2004/12/10 17:44
L22	1	("5645977").PN.	US-PGPUB; USPAT	OR	OFF	2004/12/10 17:44
L23	13	("5234571"   "5298366").PN. OR ("5645977").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/10 17:44
S1	6	"1088642"	EPO; DERWENT	OR	ON	2004/12/08 16:57
S2	25	silicon and molds	IBM_TDB	OR	ON	2004/12/08 12:14
S3	6	"4307869"	EPO; DERWENT	OR	ON	2004/12/08 12:28
S4	1	1994-286599.NRAN.	DERWENT	OR	ON	2004/12/08 12:15
S6	55	("425"/\$.ccls. or "249"/\$.ccls. or "264"/\$.ccls.) and (micron or submicron).ti.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/08 12:57
S7	561	(425/810).CCLS.	US-PGPUB; USPAT	OR	OFF	2004/12/08 12:34
S8	6	S7 and (silicon with stamper)	US-PGPUB; USPAT	OR	ON	2004/12/08 17:46
S9	8	S7 and (silicon same stamper)	US-PGPUB; USPAT	OR	ON	2004/12/08 12:36
S10	2	((optical with (disk or disc)) and mold).ti. and (silicon with stamper)	EPO; JPO; DERWENT	OR	ON	2004/12/08 12:38

S11	0	((optical with (disk or disc)) and mold).ti. and (silicon with stamper)	US-PGPUB; USPAT	OR	ON	2004/12/08 12:38
S13	17	((optical with (disk or disc)) and mold) and (silicon with stamper)	US-PGPUB; USPAT	OR	ON	2004/12/08 12:42
S14	3	"0437345"	EPO; DERWENT	OR	ON	2004/12/08 12:42
S15	5	"437345"	EPO; DERWENT	OR	ON	2004/12/08 12:44
S16	9	"74764"	EPO; DERWENT	OR	ON	2004/12/08 12:49
S17	0	(injection with (mold or mould)).ti. and microreplication	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/08 12:50
S18	28	(injection with (mold or mould)) and microreplication	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/08 12:50
S19	13	("0086660"   "20020035854"   "20030102591"   "3399425"   "3822857"   "4208368"   "4846938"   "5077870"   "5688193"   "5845375"   "6223401").PN. OR ("6824378").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/08 12:54
S20	31	("425"/\$.ccls. or "249"/\$.ccls. or "264"/\$.ccls.) and microreplication	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/08 13:00
S21	1	("5772905").PN.	US-PGPUB; USPAT	OR	OFF	2004/12/08 13:00
S22	45	("3743842"   "4310743"   "4325779"   "4383026"   "4450358"   "4498009"   "4516253"   "4552615"   "4576678"   "4606788"   "4731155"   "4832790"   "5277749").PN. OR ("5772905").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/08 13:06
S23	1	("5501784").PN.	US-PGPUB; USPAT	OR	OFF	2004/12/08 13:06
S24	14	("4661212"   "5055163"   "5234571").PN. OR ("5501784").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/08 13:12
S25	1	("5234571").PN.	US-PGPUB; USPAT	OR	OFF	2004/12/08 13:12

S26	15	("5234571").URPN.	USPAT	OR	ON	2004/12/08 13:13
S29	313	"425"/\$.ccls. and (injection adj (mold or mould)) and (insert with cavity)	USPAT	OR	ON	2004/12/08 16:59
S30	561	(425/810).CCLS.	US-PGPUB; USPAT	OR	OFF	2004/12/08 17:46
S31	8	S30 and (silicon same stamper)	US-PGPUB; USPAT	OR	ON	2004/12/08 17:46
S32	19	"425"/\$.ccls. and (injection with (mold or mould)) and (silicon with (bond or bonded or adhesive))	US-PGPUB; USPAT	OR	ON	2004/12/10 16:42
S33	244	(mold or mould) and (silicon with cavity) and (microstructures or microreplication)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/08 17:54
S34	1	("5,110,514").PN.	US-PGPUB; USPAT	OR	OFF	2004/12/08 17:54